

A	2016-3				
B	2019-4-12		R θ JA=625 SOT363-6L SOT-363		
C	2019-4-20				
D	2020-11-10				
E	2021-10-16	4			

/ Descriptions

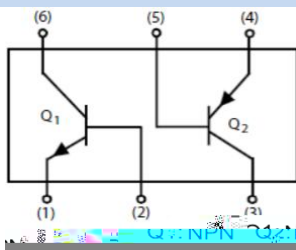
SOT-363 PNP+NPN

/ Features

h_{FE} $V_{CE(sat)}$

/ Applications

/ Equivalent Circuit

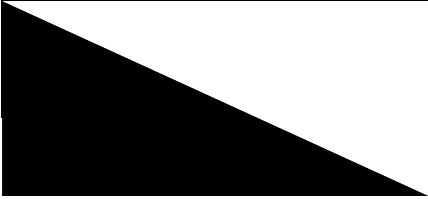


/ Pinning

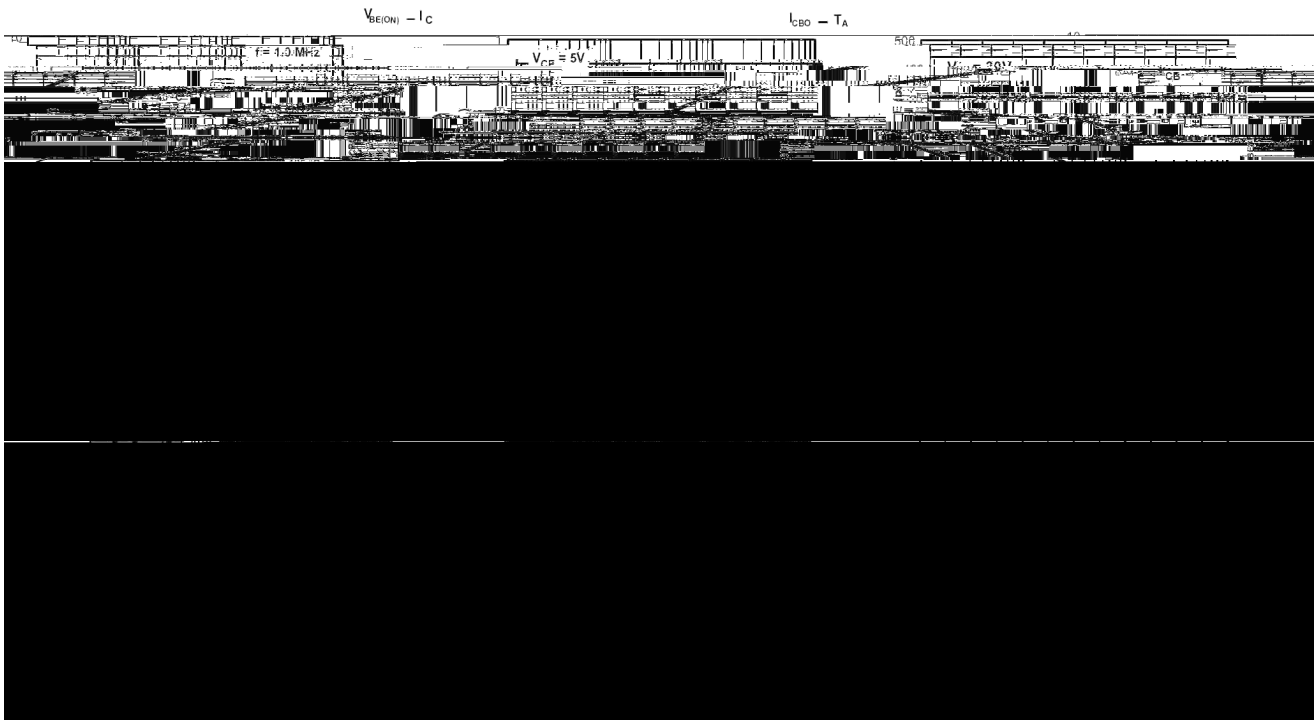


/ h_{FE} Classifications & Marking

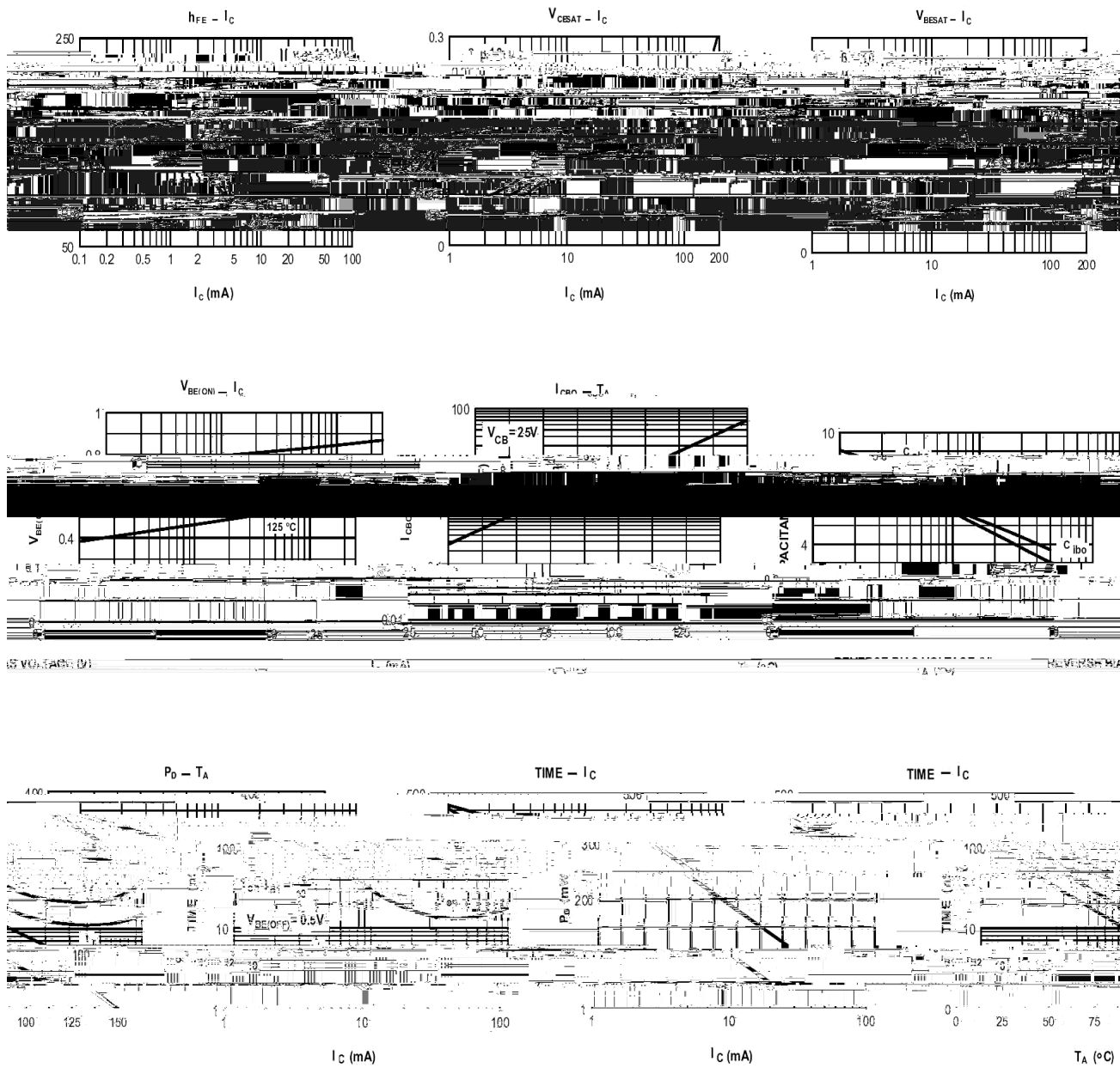
		~	

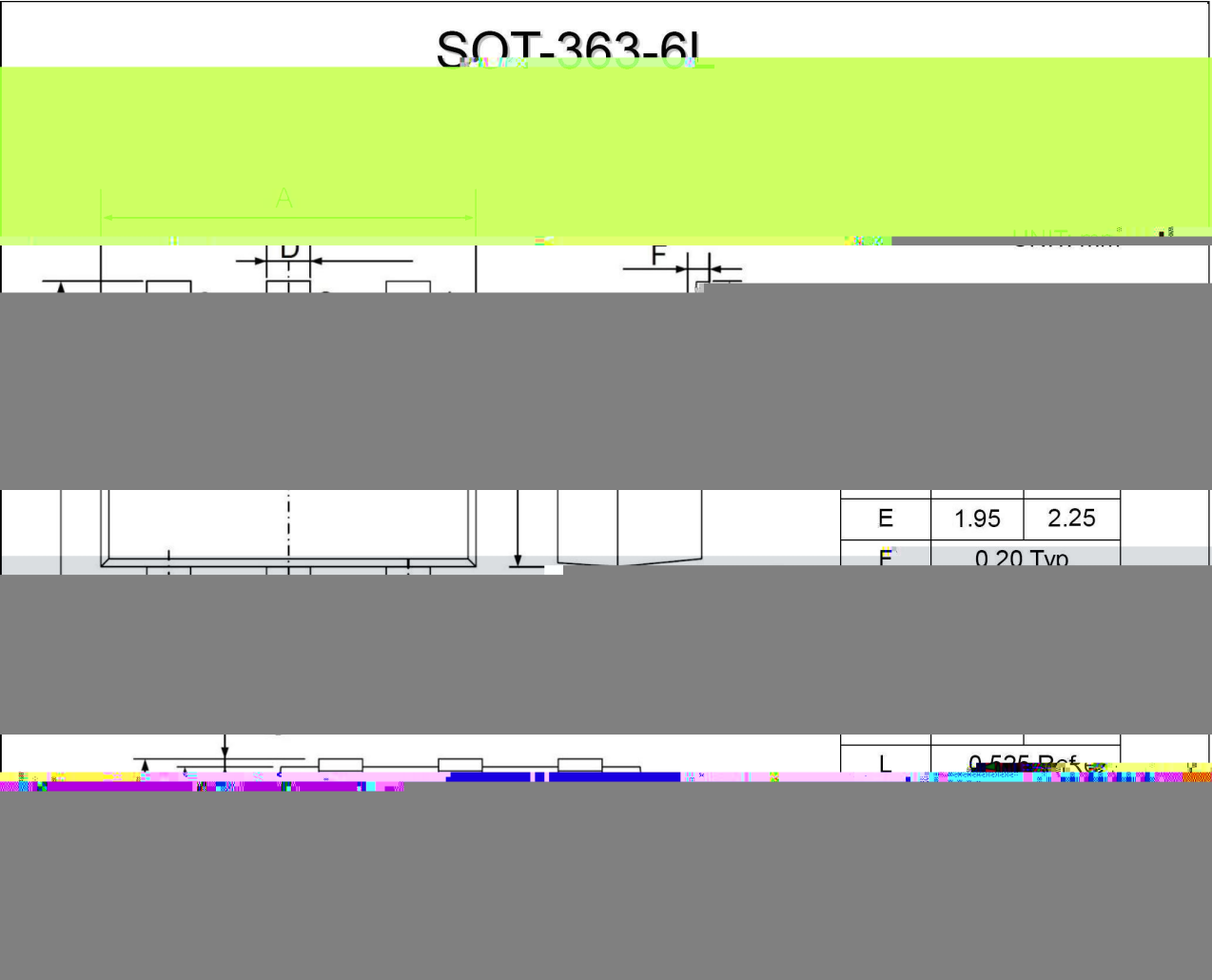
/ Electrical Characteristic Curve (NPN)



/ Electrical Characteristic Curve (PNP)



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)

$\pm$ $\pm$ $\pm$ $\pm$

/ Resistance to Soldering Heat Test Conditions

$\pm$ $\pm$

/ Packaging SPEC.

封装形式

包装数量

包装尺寸

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